**Product data sheet** 

## 1. General description

WG50N65HAW1 uses advanced Fine Trench Field-stop IGBT technology with antiparallel diode in TO247 package to provide extremely low  $V_{\text{CE(sat)}}$ , and excellent switching performance. This device offers Best-in-Class efficiency in hard switching and resonant topology.



### 2. Features and benefits

- · Maximum junction temperature 175 °C
- · Positive Temperature efficient for easy paralleling
- · Very soft, fast recovery anti-parallel diode
- · High speed switching
- · EMI Improved Design

## 3. Applications

- PFC
- Solar converters
- UPS
- Welding Converters
- · Mid to high range switching frequency converters

### 4. Quick reference data

#### Table 1. Quick reference data

Symbol	Parameter	Parameter			Value			
V <sub>CE</sub>	Collector-emitter voltage, T <sub>j</sub> ≥ 25 °C			650			V	
I <sub>C</sub>	DC collector current, limited by $T_{j(max)}$ $T_C = 100  ^{\circ}C$				50		А	
Symbol	Parameter Conditions		Notes	Min	Тур	Max	Unit	
Static cha	Static characteristics							
V <sub>CE(sat)</sub>	Collector-emitter saturation voltage	$V_{GE} = 15 \text{ V}; I_{C} = 50 \text{ A}; T_{j} = 25 \text{ °C}$		-	1.55	1.95	V	

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# 5. Pinning information

### Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate		•C
2	С	collector		
3	E	emitter		
mb	С	mounting base; connected to collector	TO247	G E sym200

# 6. Ordering information

### **Table 3. Ordering information**

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WG50N65HAW1	TO247	WG50N65HAW1Q	Tube	30	SOT429	25-Mar-2013

## 7. Marking

### **Table 4. Marking codes**

Type number	Marking codes
WG50N65HAW1	G50N65 HAW1

# 8. Limiting values

### **Table 5. Limiting values**

Symbol	Parameter	Notes	Value	Unit
V <sub>CE</sub>	Collector-emitter voltage, T <sub>j</sub> ≥ 25 °C		650	V
I <sub>C</sub>	DC collector current, limited by $T_{j(max)}$ $T_c = 25 ^{\circ}\text{C}$ $T_c = 100 ^{\circ}\text{C}$		100 50	А
I <sub>C(puls)</sub>	Pulsed collector current, t <sub>p</sub> limited by T <sub>j(max)</sub>		150	А
-	Turn off safe operating area $V_{CE} \le 650 \text{ V}, T_j \le 175 ^{\circ}\text{C}, t_p = 1  \mu\text{s}$		150	А
I <sub>F</sub>	Diode forward current, limited by $T_{j(max)}$ $T_{c}$ = 25 °C $T_{c}$ = 100 °C		60 30	А
I <sub>Fpuls</sub>	Diode pulsed current, t <sub>p</sub> limited by T <sub>j(max)</sub>		90	Α
$V_{GE}$	Gate-emitter voltage		±20	V
P <sub>tot</sub>	Power dissipation $T_C = 25 ^{\circ}\text{C}$ Power dissipation $T_C = 100 ^{\circ}\text{C}$		454 227	W
T <sub>stg</sub>	Storage temperature		-55 to +150	°C
$T_{jmax}$	Maximum operating junction temperature		175	°C
-	Peak soldering temperture		260	°C
M	Mounting Torque with washer		0.55	Nm

### 9. Thermal characteristics

**Table 6. Thermal characteristics** 

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
R <sub>th(j-c)</sub>	IGBT thermal resistance from junction to case			-	0.33	-	K/W
R <sub>th(j-c)</sub>	Diode thermal resistance from junction to case			-	0.94	-	K/W
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient			-	40	-	K/W

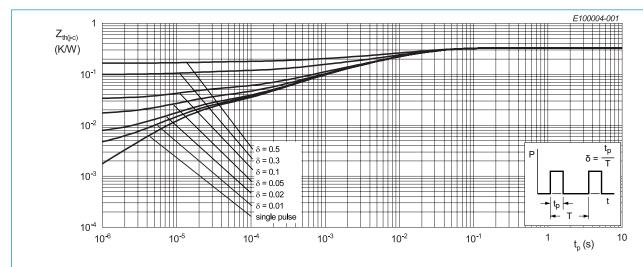


Fig. 1. Transient thermal impedance from junction to case as a function of pulse duration; IGBT

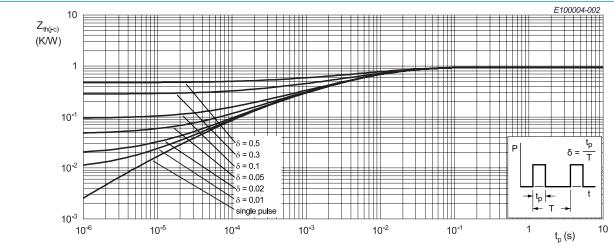


Fig. 2. Transient thermal impedance from junction to case as a function of pulse duration; Diode

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## 10. Characteristics

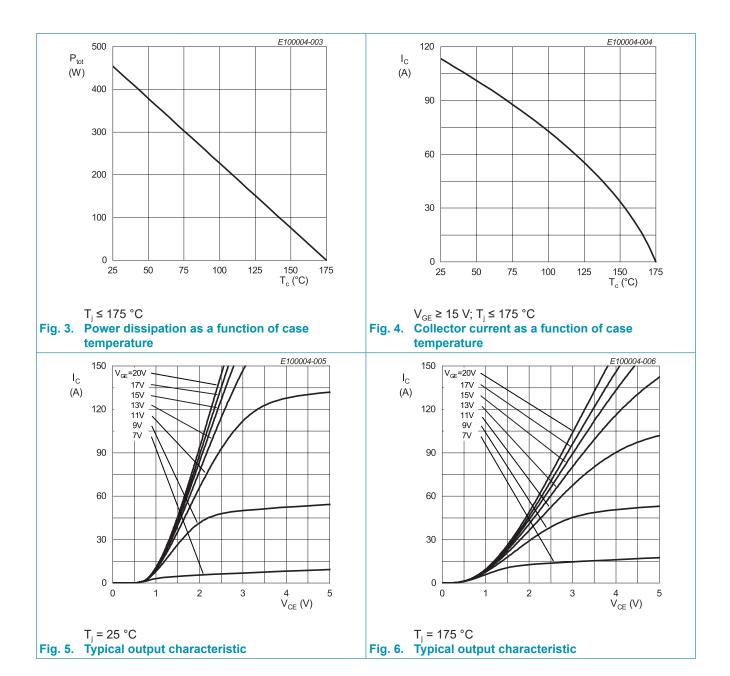
### **Table 7. Characteristics**

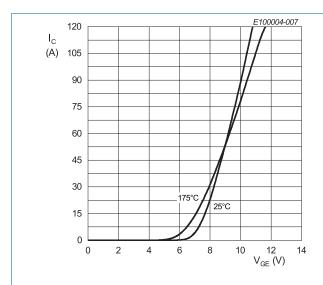
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static cha	racteristics						
BV <sub>CES</sub>	Collector-emitter breakdown voltage	$V_{GE} = 0 \text{ V}; I_{C} = 1.0 \text{ mA}$		650	-	-	V
V <sub>CE(sat)</sub>	Collector-emitter saturation	$V_{GE} = 15 \text{ V}; I_C = 50 \text{ A}; T_j = 25 ^{\circ}\text{C}$		-	1.55	1.95	V
	voltage	$V_{GE}$ = 15 V; $I_{C}$ = 50 A; $T_{j}$ = 175 °C		-	2.1	-	V
V <sub>F</sub>	Diode forward voltage	$V_{GE} = 0 \text{ V}; I_F = 30 \text{ A}; T_j = 25 \text{ °C}$		-	1.9	-	V
		$V_{GE} = 0 \text{ V}; I_F = 30 \text{ A}; T_j = 175 \text{ °C}$		-	1.5	-	V
$V_{\text{GE(th)}}$	Gate-emitter threhold voltage	$I_{\rm C}$ = 0.5 mA; $V_{\rm CE}$ = $V_{\rm GE}$		4.2	5.2	6.2	V
I <sub>CES</sub>	Zero gate voltage collector current	$V_{CE} = 650 \text{ V}; V_{GE} = 0 \text{ V}; T_j = 25 \text{ °C}$		-	-	100	μA
		$V_{CE} = 650 \text{ V}; V_{GE} = 0 \text{ V}; T_j = 175 ^{\circ}\text{C}$		-	-	1	mA
g <sub>fs</sub>	Transconductance	V <sub>CE</sub> = 20 V; I <sub>C</sub> = 50 A		-	34	-	S
Dynamic	characteristics						
C <sub>ies</sub>	Input capacitance	V <sub>CE</sub> = 30 V; V <sub>GE</sub> = 0 V; f = 1 MHz;		-	2955	-	pF
C <sub>oes</sub>	Output capacitance	T <sub>j</sub> = 25 °C		-	105	-	pF
C <sub>res</sub>	Reverse transfer capacitance			-	41	-	pF
$Q_{G}$	Gate charge	$V_{CC}$ = 520 V; $I_{C}$ = 50 A; $V_{GE}$ = 15 V; $T_{i}$ = 25 °C		-	138	-	nC

# 11. Switching Characteristics

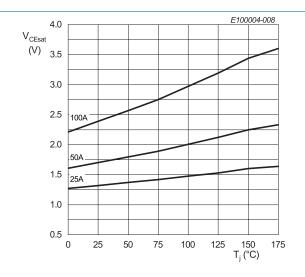
Table 8. Switching Characteristics, Inductive Load

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
IGBT cha	racteristics						
$t_{d(on)}$	Turn-on delay time	T <sub>j</sub> = 25 °C;		-	51	-	nS
t <sub>r</sub>	Rise time	$V_{CC} = 400 \text{ V}; I_C = 50 \text{ A}; V_{GE} = 15 \text{ V} / 0 \text{ V};$ $R_G = 10 \Omega$		-	51	-	nS
$t_{\text{d(off)}}$	Turn-off delay time			-	209	-	nS
t <sub>f</sub>	Fall time			-	33	-	nS
E <sub>on</sub>	Turn-on energy			-	1.24	-	mJ
E <sub>off</sub>	Turn-off energy			-	0.65	-	mJ
E <sub>ts</sub>	Total switching energy			-	1.89	-	mJ
t <sub>d(on)</sub>	Turn-on delay time	$T_{\rm j}$ = 175 °C; $V_{\rm cc}$ = 400 V; $I_{\rm c}$ = 50 A; $V_{\rm GE}$ = 15V / 0V; $R_{\rm G}$ = 10 $\Omega$		-	48	-	nS
t <sub>r</sub>	Rise time			-	49	-	nS
$t_{d(off)}$	Turn-off delay time			-	241	-	nS
t <sub>f</sub>	Fall time			-	38	-	nS
E <sub>on</sub>	Turn-on energy			-	1.88	-	mJ
E <sub>off</sub>	Turn-off energy			-	0.85	-	mJ
E <sub>ts</sub>	Total switching energy			-	2.73	-	mJ
Diode cha	aracteristics		ı				
t <sub>rr</sub>	Reverse recovery time	T <sub>j</sub> = 25 °C;		-	44	-	nS
Q <sub>r</sub>	Reverse recovery charge	$\dot{V}_R = 400 \text{ V}; I_F = 30 \text{ A}; dI_F/dt = 500 \text{A/us}$		-	221	-	nC
I <sub>RM</sub>	Reverse recovery peak current			-	9	-	А
t <sub>rr</sub>	Reverse recovery time	T <sub>j</sub> = 175 °C; V <sub>R</sub> = 400 V; I <sub>F</sub> = 30 A; dI <sub>F</sub> /dt = 500A/us		-	100	-	nS
Q <sub>r</sub>	Reverse recovery charge			-	990	-	nC
I <sub>RM</sub>	Reverse recovery peak current			-	17	-	А

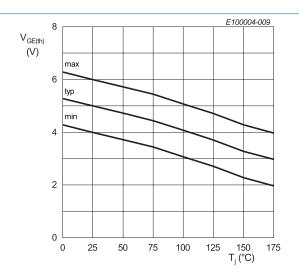




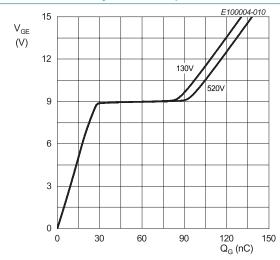
 $V_{CE}$  = 20 V Fig. 7. Typical transfer characteristic



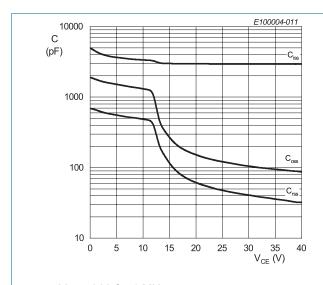
V<sub>GE</sub> = 15 V
Fig. 8. Typical collector-emitter saturation voltage as a function of junction temperature

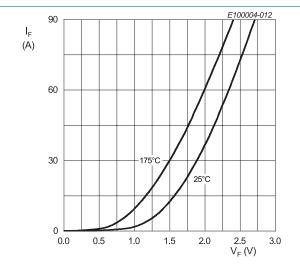


 $I_c = 500~\mu A$  Fig. 9. Gate-emitter threshold voltage as a function of junction temperature



 $I_c$  = 50 A Fig. 10. Typical gate charge



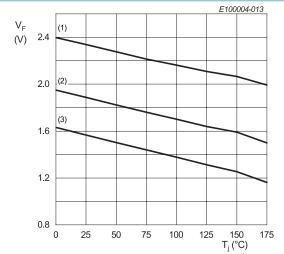


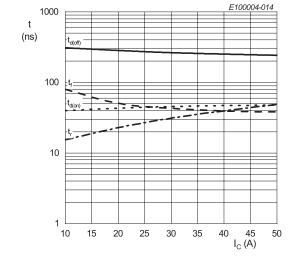
V<sub>GE</sub> = 0 V; f = 1 MHz

1. Typical capacitance as:

Fig. 12. Typical diode forward current as a function of forward voltage



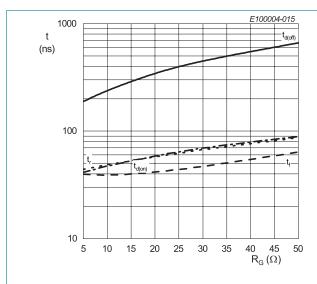




(1)  $I_F = 60 \text{ A}$ (2)  $I_F = 30 \text{ A}$   $R_{g}$  = 10  $\Omega;$   $V_{GE}$  = 15V/0V;  $T_{j}$  = 175 °C;  $V_{CE}$  = 400 V; inductive load

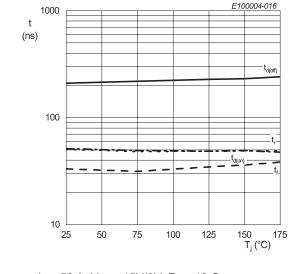
(3)  $I_F$  = 15 A Fig. 13. Typical diode forward voltage as a function of junction temperature

Fig. 14. Typical switching times as a function of collector current



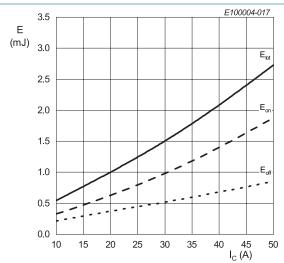
 $I_C$  = 50 A;  $V_{GE}$  = 15V/0V;  $T_j$  = 175 °C;  $V_{CE}$  = 400 V; inductive load

Fig. 15. Typical switching times as a function of gate resistance



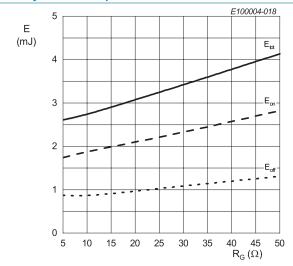
 $I_{C}$  = 50 A;  $V_{GE}$  = 15V/0V;  $R_{g}$  = 10  $\Omega$ ;  $V_{CE}$  = 400 V; inductive load

Fig. 16. Typical switching times as a function of junction temperature



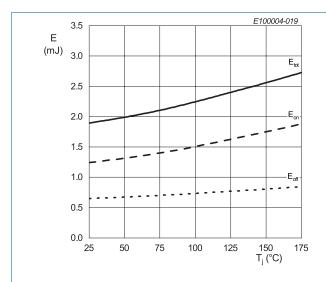
 $R_g$  = 10  $\Omega$ ;  $V_{GE}$  = 15V/0V;  $T_j$  = 175 °C;  $V_{CE}$  = 400 V; inductive load

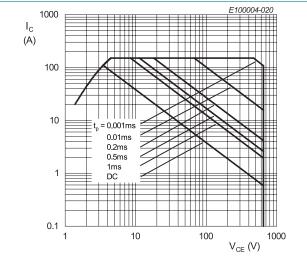
Fig. 17. Typical switching energy losses as a function of collector current



 $I_{\text{C}}$  = 50 A;  $V_{\text{GE}}$  = 15V/0V;  $T_{j}$  = 175 °C;  $V_{\text{CE}}$  = 400 V; inductive load

Fig. 18. Typical switching energy losses as a function of gate resistance





 $I_{C}$  = 50 A;  $V_{GE}$  = 15V/0V;  $R_{g}$  = 10  $\Omega;$   $V_{CE}$  = 400 V; inductive load

Fig. 20. Forward bias safe operating area

Fig. 19. Typical switching energy losses as a function of junction temperature

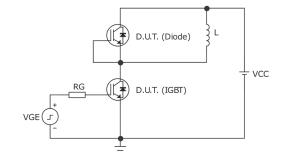


Fig. 21. Test circuit for inductive load switching

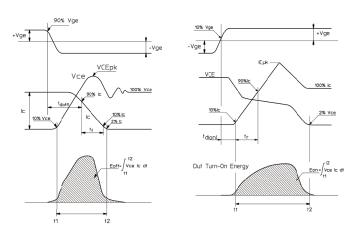
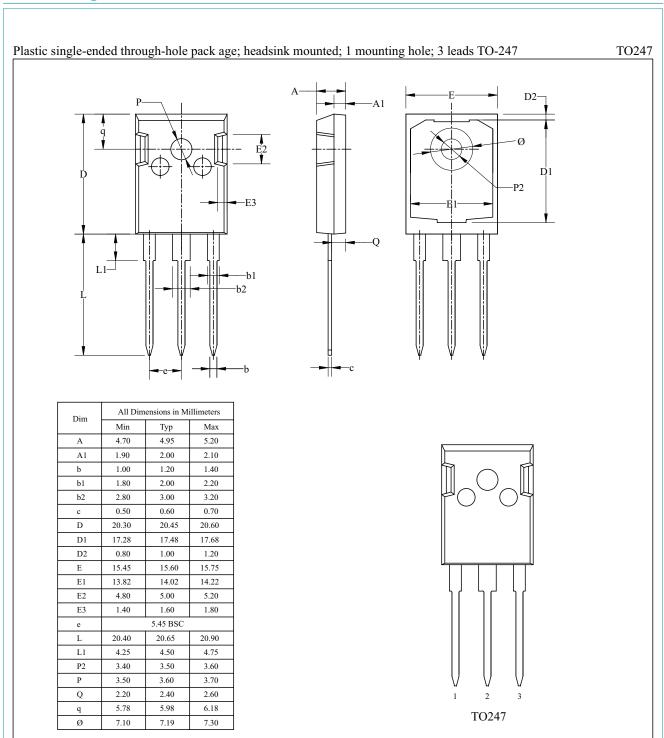


Fig. 22. Definition of switching times and losses

## 12. Package outline



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### 13. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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